MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

VHF/UHF Transistor

NPN Silicon

Features

- S and NSV Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---------------------------|------------------|-------|------|
| Collector-Emitter Voltage | V_{CEO} | 25 | Vdc |
| Collector-Base Voltage | V_{CBO} | 30 | Vdc |
| Emitter-Base Voltage | V _{EBO} | 3.0 | Vdc |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|-----------------------------------|----------------|-------------|
| Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C | P _D | 225 1.8 | mW mW/°C |
| Thermal Resistance, Junction to Ambient (Note 1) | $R_{	heta JA}$ | 556 | °C/W |
| Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C Derate above 25°C | P _D | 300 2.4 | mW mW/°C |
| Thermal Resistance, Junction to Ambient (Note 2) | $R_{	heta JA}$ | 417 | °C/W |
| Junction and Storage Temperature Range | T _J , T _{stg} | –55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

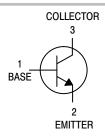
- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina



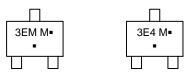
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MARKING DIAGRAMS



MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-04LT1G

3EM, 3E4= Specific Device Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------------------------|---------------------|-------------------------|
| MMBTH10LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| NSVMMBTH10LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| MMBTH10-4LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| MMBTH10LT3G, SMMBTH10-4LT3G | SOT-23 (Pb-Free) | 10,000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|----------------------|------------|--------|----------|------|
| OFF CHARACTERISTICS | | | • | • | - |
| Collector–Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$ | V _{(BR)CEO} | 25 | _ | - | Vdc |
| Collector–Base Breakdown Voltage (I _C = 100 μAdc, I _E = 0) | V _{(BR)CBO} | 30 | - | - | Vdc |
| Emitter–Base Breakdown Voltage $(I_E = 10 \mu Adc, I_C = 0)$ | V _{(BR)EBO} | 3.0 | - | _ | Vdc |
| Collector Cutoff Current (V _{CB} = 25 Vdc, I _E = 0) | Ісво | - | - | 100 | nAdc |
| Emitter Cutoff Current (V _{EB} = 2.0 Vdc, I _C = 0) | I _{EBO} | - | _ | 100 | nAdc |
| ON CHARACTERISTICS | | | • | • | - |
| DC Current Gain ($I_C = 4.0$ mAdc, $V_{CE} = 10$ Vdc) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-4LT1G, SMMBTH10-4LT3G | h _{FE} | 60 120 | _ _ | _ 240 | - |
| Collector–Emitter Saturation Voltage (I _C = 4.0 mAdc, I _B = 0.4 mAdc) | V _{CE(sat)} | _ | _ | 0.5 | Vdc |
| Base–Emitter On Voltage (I _C = 4.0 mAdc, V _{CE} = 10 Vdc) | V _{BE} | - | - | 0.95 | Vdc |
| SMALL-SIGNAL CHARACTERISTICS | | | • | | • |
| Current–Gain – Bandwidth Product (I _C = 4.0 mAdc, V _{CE} = 10 Vdc, f = 100 Mhz) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10–4LT1G, SMMBTH10–4LT3G | f _T | 650 800 | _ _ | _ _ | MHz |
| Collector–Base Capacitance $(V_{CB}=10 \text{ Vdc}, I_E=0, f=1.0 \text{ MHz})$ | C _{cb} | - | - | 0.7 | pF |
| Common–Base Feedback Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz) | C _{rb} | - | - | 0.65 | pF |
| Collector Base Time Constant (I _C = 4.0 mAdc, V _{CB} = 10 Vdc, f = 31.8 MHz) | rb′C _c | - | - | 9.0 | ps |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

TYPICAL CHARACTERISTICS

COMMON-BASE y PARAMETERS versus FREQUENCY

 $(V_{CB} = 10 \text{ Vdc}, I_{C} = 4.0 \text{ mAdc}, T_{A} = 25^{\circ}\text{C})$

yib, INPUT ADMITTANCE

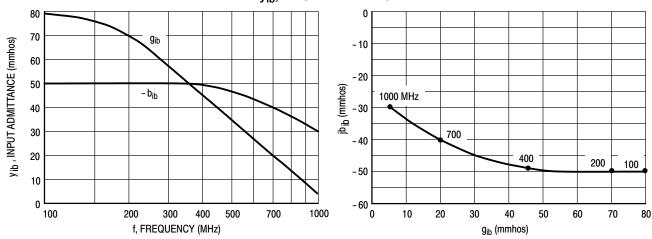


Figure 1. Rectangular Form

Figure 2. Polar Form

y_{fb}, FORWARD TRANSFER ADMITTANCE

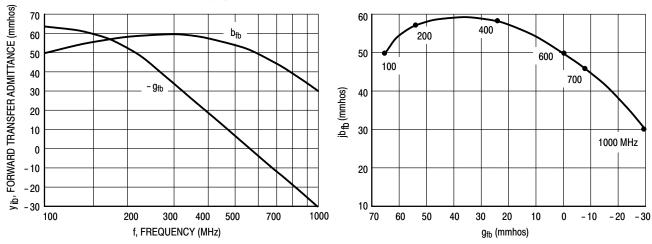


Figure 3. Rectangular Form

Figure 4. Polar Form

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

TYPICAL CHARACTERISTICS

COMMON-BASE y PARAMETERS versus FREQUENCY

 $(V_{CB} = 10 \text{ Vdc}, I_C = 4.0 \text{ mAdc}, T_A = 25^{\circ}\text{C})$

y_{rb}, REVERSE TRANSFER ADMITTANCE

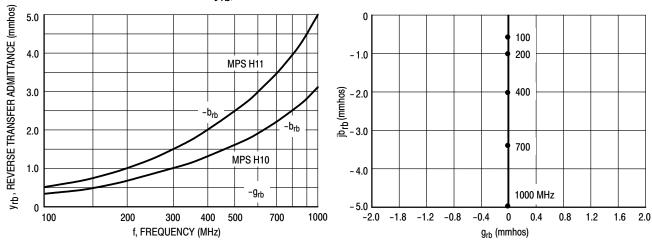


Figure 5. Rectangular Form

Figure 6. Polar Form

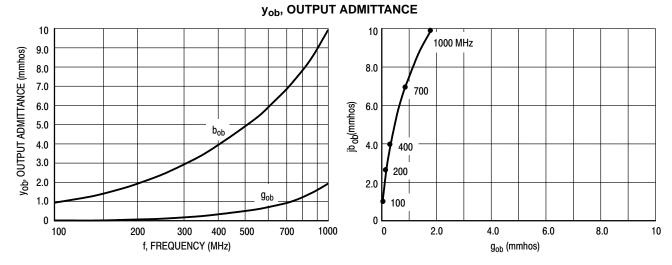


Figure 7. Rectangular Form

Figure 8. Polar Form



SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

DATE 30 JAN 2018

SCALE 4:1 D - 3X b

TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

| | PROT | RUSIONS, OR GATE BURRS. | |
|--|------|-------------------------|--|
|--|------|-------------------------|--|

| | MILLIMETERS | | | | INCHES | |
|-----|-------------|------|------|-------|--------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| С | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| е | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| Т | 0° | | 10° | 0° | | 10° |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

| STYLE 1 THRU 5: CANCELLED | STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR | STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR | STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE |
|------------------------------|---|---|--|
| OT (1 F O | | | |

SOT-23 (TO-236)

| STYLE 9: | STYLE 10: | STYLE 11: | STYLE 12: | STYLE 13: | STYLE 14: |
|---------------------------|--------------------------|---------------------------------|---------------------------|---------------|-------------------------|
| PIN 1. ANODE | PIN 1. DRAIN | PIN 1. ANODE | PIN 1. CATHODE | PIN 1. SOURCE | PIN 1. CATHODE |
| ANODE | SOURCE | CATHODE | CATHODE | 2. DRAIN | 2. GATE |
| CATHODE | 3. GATE | CATHODE-ANODE | ANODE | 3. GATE | ANODE |

| STYLE 15: | STYLE 16: | STYLE 17: | STYLE 18: | STYLE 19: | STYLE 20: |
|---------------------------|---------------------------|---------------------------|---------------------------|--------------------------------|-------------------------|
| PIN 1. GATE | PIN 1. ANODE | PIN 1. NO CONNECTION | PIN 1. NO CONNECTION | PIN 1. CATHODE | PIN 1. CATHODE |
| CATHODE | CATHODE | 2. ANODE | CATHODE | 2. ANODE | ANODE |
| ANODE | CATHODE | CATHODE | ANODE | CATHODE-ANOD | E 3. GATE |

| STYLE 21: | STYLE 22: | STYLE 23: | STYLE 24: | STYLE 25: | STYLE 26: |
|--------------------------|--------------------------|--------------|-------------|--------------|---------------------------------|
| PIN 1. GATE | PIN 1. RETURN | PIN 1. ANODE | PIN 1. GATE | PIN 1. ANODE | PIN 1. CATHODE |
| SOURCE | OUTPUT | 2. ANODE | 2. DRAIN | 2. CATHODE | 2. ANODE |
| 3 DRAIN | 3 INPLIT | 3 CATHODE | 3. SOURCE | 3. GATE | NO CONNECTION |

| STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE | STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE | |
|---|---|--|
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